UL 796F

STANDARD FOR SAFETY

Flexible Materials Interconnect Constructions

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UL Standard for Safety for Flexible Materials Interconnect Constructions, UL 796F

Fourth Edition, Dated February 26, 2021

Summary of Topics

This revision of ANSI/UL 796F dated October 6, 2023 includes the following:

– Addition of Constructions Not Currently Covered; 1.7 and 1.8

– Editorial Corrections; 6.64, 9.4.1, 12.12.2.1, 12.14 (title)

– Clarification of Polyimide ANSI-like Flammability Program; 8.2.2

– Harmonization of Bond Strength Test Pattern; 8.4.16, Figure 12.8

– Addition of Conductive Coin Requirements; 8.4.22A – 8.4.22C

– Alignment of Via Hole Requirements between UL 796F and UL 796; 8.4.26, 8.4.26A, 8.4.26B, 8.8.1, Figure 8.4A, Figure 12.8

– Delete Option for PWB Manufacturer to Test for Higher Performance Index Values; 9.4.6

Text that has been changed in any manner or impacted by ULSE's electronic publishing system is marked with a vertical line in the margin.

The news and revised requirements are substantially in accordance with Proposal(s) on this subject dated June 30, 2023.

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Comments or proposals for revisions on any part of the Standard may be submitted to ULSE at any time. Proposals should be submitted via a Proposal Request in the Collaborative Standards Development System (CSDS) at https://csds.ul.com.

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CONTENTS

INTRODUCTION

1 Scope 5
2 Units of Measurement 5
3 Supplementary Test Procedures....5
4 References....6
5 General 6
6 Glossary....7
7 Abbreviations....18

CONSTRUCTION

8 Materials 18
 8.1 General 18
 8.2 Polyimide ANSI-like flammability program 20
 8.3 Base materials 20
 8.4 Conductors and conductor adhesives....22
 8.5 Bonding film (supported and unsupported) and internal bonding materials 27
 8.6 Cover material (coverlay, coverfilm and covercoat)....29
 8.7 Solder resist, solder mask, and permanent coatings....31
 8.8 Plugged-hole materials 32
 8.9 High density interconnect (HDI) dielectric materials....34
 8.10 Stiffener and adhesive (external bonding) materials....37
9 FMIC Constructions....39
 9.1 General 39
 9.2 Singlelayer (dielectrics)....41
 9.3 Multilayer (dielectrics) 43
 9.4 Dissimilar dielectric materials evaluation 45
 9.5 Mass laminate multilayer (dielectrics)....46
 9.6 Flexible....46
 9.7 Flex-to-install 47
 9.8 Rigid....47
 9.9 Multilayer rigid flex composite....48
 9.10 Flammability classification only 52
 9.11 Glossary of construction and FMIC titles 52
10 Processes 54
 10.1 General....54
 10.2 Process description 54
 10.3 Variations in processes 54
11 Parameter Profile Indices 55
 11.1 General....55
 11.2 Maximum operating temperature (MOT) 56
 11.3 Flammability classification 57
 11.4 Assembly soldering process – solder limits 57
 11.5 Thickness....58
 11.6 Conductor weight....58
 11.7 Conductor width....58
 11.8 Maximum area conductor diameter 59
 11.9 Direct support requirements (DSR)....59

PERFORMANCE

12 Tests 60

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12.1 General.......60
12.2 Microsection analysis.......69
12.3 Thermal stress test.......71
12.4 Delamination test.......73
12.5 Plating adhesion test.......75
12.6 Bond strength test.......78
12.7 Conductive paste adhesion test.......84
12.8 Coverlay test.......89
12.9 (Ambient) bend test.......91
12.10 Cold-bend test.......95
12.11 Repeated flexing test.......97
12.12 Stiffener bond strength test.......101
12.13 Silver migration test.......108
12.14 Dissimilar dielectric materials delamination test.......113
12.15 Flammability tests.......115
12.16 Direct support requirements (DSR) tests.......119

MARKINGS

13 Markings.......119
13.1 General.......119
13.2 Type designation.......120
13.3 Trademark.......120
13.4 Manufacturer identification.......120
13.5 FMIC category constructions.......120
13.6 Flammability classification.......121
13.7 Flammability classification only constructions.......121
13.8 Direct support requirements (DSR).......121
13.9 Comparative tracking index (CTI).......121
13.10 System component symbol (SCS).......122
13.11 Size class number (SCN).......122
13.12 Additional stiffener and adhesive (external bonding) materials.......123

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INTRODUCTION

1 Scope

1.1 These requirements apply to flexible material printed wiring board constructions (FMIC's) for use as components in flexible, flex-to-install, rigid, and multilayer rigid-flex composite applications with and without stiffener and adhesive materials in devices or appliances.

1.2 Together with the Standards mentioned in the Supplementary Test Procedures, Section 3, these requirements provide data with respect to the physical, electrical, flammability, thermal, and other properties of the FMIC under consideration and are intended to provide guidance to the fabricator, end product manufacturer, safety engineers and other interested parties.

1.3 Compliance with these requirements does not indicate the product is acceptable for use as a component of an end product without further investigation.

1.4 The singlelayer and multilayer flexible, flex-to-install, and multilayer rigid-flex composite constructions addressed by these requirements consist of conductors affixed to base material, with mid-board interconnections, and cover materials.

1.5 The suitability of additional stiffener and adhesive materials, not evaluated in accordance with Stiffener and adhesive (external bonding) materials, 8.10, the Stiffener bond strength test, 12.12, and Flammability tests, 12.15, are subject to the applicable end-use product construction and performance requirements. See Additional stiffener and adhesive (external bonding) materials, 13.12, for marking requirements for FMIC's provided with additional stiffener and adhesive materials not investigated.

1.6 The requirements for rigid printed wiring boards are in the Standard for Printed Wiring Boards, UL 796.

1.7 The evaluation of printed wiring boards that are produced using additive manufacturing (AM) processes, commonly referred to as 3D printing, are to be evaluated under the appropriate clauses of this Standard based on the board application.

1.8 For constructions and materials not specifically addressed in this Standard:

- The printed wiring board should provide safeguards not less than that generally afforded by this document and the principles of safety contained herein. This includes printed wiring boards with technologies, materials, or methods of construction, including the manufacturing process, not specifically addressed in this document.

- Propose for discussion with the Technical Committee the need for additional detailed requirements to address a new situation in a timely manner.

2 Units of Measurement

2.1 Values stated without parentheses are the requirement. Values in parentheses are explanatory or approximate information.

3 Supplementary Test Procedures

3.1 These requirements are intended to be used in conjunction with the following requirements or standards:

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a) The Standard for Polymeric Materials – Short Term Property Evaluations, UL 746A, the Standard for Polymeric Materials – Long Term Property Evaluations, UL 746B, the Standard for Polymeric Materials – Industrial Laminates, Filament Wound Tubing, Vulcanized Fibre, and Materials Used in Printed Wiring Boards, UL 746E, and the Standard for Polymeric Materials – Flexible Dielectric Film Materials for Use in Printed Wiring Boards and Flexible Materials Interconnect Constructions, UL 746F, contain programs for investigating polymeric materials and industrial laminates.

b) The Standard for Tests for Flammability of Plastic Materials for Parts in Devices and Appliances, UL 94, contains methods for evaluating the flammability of polymeric materials that are intended to be used in electrical equipment.

c) The Standard for Printed Wiring Boards, UL 796, covers the minimum performance requirements for rigid printed wiring boards.

4 References

4.1 Any undated reference to a code or standard appearing in the requirements of this standard shall be interpreted as referring to the latest edition of that code or standard.

4.2 The following publications are referenced in this standard:

ASTM D 149 – Standard Test Method for Dielectric Breakdown Voltage and Dielectric Strength of Solid Electrical Insulating Materials at Commercial Power Frequencies.

ASTM D 374 – Standard Test Methods for Thickness of Solid Electrical Insulation.

ASTM D 1000 – Standard Test Methods for Pressure-Sensitive Adhesive-Coated Tapes Used for Electrical and Electronic Applications.

ASTM D 5374 – Standard Test Methods for Forced-Convection Laboratory Ovens for Evaluation of Electrical Insulation.

ASTM D 5423 – Standard Specification for Forced-Convection Laboratory Ovens for Evaluation of Electrical Insulation.

ASTM D 618 – Standard Practice for Conditioning Plastics for Testing

ASTM E 3 – Standard Practice for Preparation of Metallographic Specimens.

IPC TM-650 2.1.1 – Microsectioning, Manual and Semi or Automatic Method.

ISO 291 – Plastics – Standard Atmospheres for Conditioning and Testing.

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5 General

5.1 Acceptability of an FMIC in a device or appliance depends on the acceptability of the construction for:

a) Continued use under actual service conditions, including the maximum operating temperature (MOT);

b) Flammability properties; and

c) All other applicable end-product requirements.

5.2 The investigation of an FMIC shall include consideration of the conductor properties, such as weight (thickness), minimum midboard and edge width, and maximum ground plane area, and shall include the conductor forming and materials build-up processes including solder limits.

5.3 Except as indicated in 5.4, the factors considered in testing the FMIC conductor supporting material in its application shall include mechanical strength, moisture absorption, combustibility, resistance to ignition from electrical sources, dielectric strength, insulation resistance, resistance to arc-tracking, and resistance to creeping and distortion at temperatures to which the material is subjected in the end product. The conductor supporting material shall not display a loss of these properties beyond the minimum acceptable level as a result of aging, and relative temperature indices shall be assigned to the conductor supporting material.

5.4 If an FMIC is entitled with flammability classification only, the acceptability of the FMIC shall involve only flammability tests. See Flammability tests, 12.15.

5.5 An FMIC entitled flexible is intended for use where the construction is subject to dynamic flexing applications, yet the flexural endurance of the construction has not been evaluated.

5.6 An FMIC entitled flex-to-install is intended for use where the construction is flexed for installation or service (only) and shall not be subject to dynamic or repeated flexing applications, yet the flexural endurance of the construction has not been evaluated.

5.7 An FMIC entitled rigid is intended for use where the construction is not flexed or subject to dynamic or repeated flexing applications.

5.8 Multilayer rigid flex composite constructions may include single-sided, double-sided, singlelayer and multilayer flexible, flex-to-install, and rigid constructions in various sections of an FMIC.

6 Glossary

6.1 For the purpose of this Standard the following definitions shall apply.

6.2 ACCESS HOLE – Holes on the same axis through successive layers of materials intended to provide access to the surface of the land on an inner conductor layer of a multilayer category construction.

6.3 ADDITIVE PROCESS – A selective or non-selective process used to deposit a pattern of conductor material(s) on clad or unclad base material.

6.4 ADD-ON COMPONENT – Discrete, integrated, packaged, or chip components that are attached to an FMIC to function as part of a complete circuit or assembly.

6.5 ADHESIVE – A substance such as glue or cement used to join, bond, or fasten materials or objects together.

6.6 AS-RECEIVED – Samples or samples in an unconditioned state, prior to being subject to conditioning, or without a history of conditioning.

6.7 ASSEMBLY – Various parts, subassemblies, and combinations thereof, joined together.

6.8 BARE BOARD – An unpopulated FMIC without add-on or embedded components or assemblies.

6.9 BASE DIELECTRIC MATERIAL – An organic or inorganic dielectric barrier material, used to support conductor material.

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6.10 BASE MATERIAL – An organic or inorganic insulating material used to support a pattern of conductor material, with or without integral adhesive material, with or without integral conductor material.

6.11 BASE MATERIAL THICKNESS – The thickness of the base dielectric material excluding conductive foil or material deposited on the surfaces. If an adhesive is used for the base material, the adhesive thickness and number of sides is indicated separately.

6.12 BLIND VIA – A via extending to only one surface of the printed wiring board construction.

6.13 BLISTERING – Localized area of delamination. See Delamination, 6.60.

6.14 BONDING FILM– The layer of insulation used to bond discrete layers during lamination of multilayer flexible printed wiring board constructions. A general term used to describe bondply and freefilm. See also Bond Ply 6.16, Supported Bonding Film, 6.162, Freefilm, 6.87, and Unsupported Bonding Film, 6.174.

6.15 BONDING LAYER – An adhesive layer used to bond discrete layers of multilayer category constructions during lamination.

6.16 BOND PLY – See Bonding Film, 6.14.

6.17 BUILD-UP MATERIAL – Multiple layers of HDI materials.

6.18 BUILD-UP THICKNESS – Overall thickness of a combination of materials. Unless otherwise indicated, the build-up thickness will refer to the overall thickness in the area of an FMIC where no internal or external conductor material resides.

6.19 BURIED VIA – A via that does not extend to the surface of an FMIC construction.

6.20 CALCULATED THICKNESS – A thickness value determined by adding suggested material component thicknesses, or a thickness value determined by adding or subtracting one measured value to or from another measured value.

6.21 CAST ON COPPER – Resin is cast onto copper and then polymerized (cured). The process may require a “multilayer” resin to manufacture a double-sided clad material.

6.22 CIRCUIT – Electrical devices and elements interconnected to perform a desired electrical function.

6.23 CIRCUITRY LAYER – Conductor layer or plane in or on an FMIC construction or printed board.

6.24 CLAD MATERIAL – Base material or base dielectric material with conductor material attached.

6.25 CLADDING – A deposited or plated metallic layer or laminated foil used for its protective and/or electrical properties. See Conductive Foil, 6.30.

6.26 COATING – A non-metallic substance applied by some process, such as dipping, curtain coating, film laminating, screening, spraying, or melt-flow.

6.27 COMPONENT – An individual or combination of parts intended to perform a desired function.

6.28 CONDITIONING – The time related exposure of test samples to a specified environment for a period of time, prior to or after testing, and before evaluation.

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6.29 CONDUCTIVE (ELECTRICAL) – The ability of a substance or material to conduct electricity.

6.30 CONDUCTIVE FOIL – A thin metal sheet intended for forming a conductor pattern on a base material.

6.31 CONDUCTIVE PASTE – An organic or inorganic paste substance capable of transmitting electricity, used for circuit conductors, including but not limited to carbon, copper, and silver.

6.32 CONDUCTIVITY (ELECTRICAL) – A property exhibited by a material or substance when electricity is transmitted through the material or substance.

6.33 CONDUCTOR – A trace or path for electricity to transmit in a conductor pattern.

6.34 CONDUCTOR ADHESIVE – Adhesive material used to attach conductor material to a base material, or base dielectric material.

6.35 CONDUCTOR AVERAGE TRACE WIDTH – The average width of a length of conductor trace.

6.36 CONDUCTOR BASE WIDTH – The width of a conductor at the interface of the conductor material and base material. See Conductor Width, 6.44.

6.37 CONDUCTOR LAYER – The total conductive pattern formed on one side of a single layer of a base material. This may include all or a portion of ground and voltage planes.

6.38 CONDUCTOR MATERIAL – An organic or inorganic substance capable of transmitting electricity, used for circuit conductors, including but not limited to copper, tin, nickel, gold, copper paste, silver paste, carbon paste, ruthenium oxide paste, etc.

6.39 CONDUCTOR PATTERN – The path, design, or configuration of conductor material on the base material, including but not limited to conductor traces, lands, through-holes, and vias.

6.40 CONDUCTOR SPACING – The minimum distance between adjacent conductors.

6.41 CONDUCTOR THICKNESS – The thickness of the conductor and additional metallic platings or coatings, excluding non-conductive coatings.

6.42 CONDUCTOR TRACE – A linear conductor path of a conductor circuit.

6.43 CONDUCTOR WEIGHT – See Conductor Thickness, 6.41.

6.44 CONDUCTOR WIDTH – The width of the conductor as viewed from a top view or at the plane of the surface of a base material, whichever is less. See Conductor Base Width, 6.36.

6.45 CONFORMAL COATING – An insulating, environmentally protective coating capable of conforming to the objects coated.

6.46 CONNECTOR – A terminal device capable of connect/disconnect service for electrical components.

6.47 CONSTRUCTION – A variation in flexible materials build-up, including but not limited to film, adhesive, base material, bonding film, cover material, dielectric material, laminate, prepreg, or other insulation materials. Variations include singlelayer, multilayer, flexible, flex-to-install, rigid, and multilayer flex-rigid composite constructions.

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6.48 CONTACT FINGER – A conductive surface used to provide electrical connection by pressure contact, usually located at an edge of an FMIC.

6.49 CONTINUITY – An uninterrupted path for the flow of electrical current in a circuit.

6.50 CONVERTOR – Manufacturer who prepares materials, such as lamination of copper, adhesive, and base dielectric material for use in the fabrication of FMIC's.

6.51 CORE MATERIAL – The innermost material, FMIC construction, or printed wiring board which may be used to support a subsequent layer or layers of dielectric material and conductor pattern. Core material may be an organic or inorganic material, with or without integral dielectric material. Core material may be referred to as substrate material.

6.52 COVERCOAT – A material deposited as a liquid onto the circuitry that subsequently becomes a permanent dielectric coating. See Cover Material, 6.56.

6.53 COVERFILM – A film made from:

a) A homogenous, single component chemistry;

b) Separate layers of generically similar chemistries; or

c) A composite blend of chemistries.

See Cover Material, 6.56.

6.54 COVERLAY– Film and adhesive made from separate layers of generically different chemistries. See Cover Material, 6.56.

6.55 COVERLAY ADHESIVE – Adhesive used with film to prepare coverlay.

6.56 COVER MATERIAL – A thin dielectric material used to encapsulate circuitry, most commonly for flexible circuit applications. See Covercoat, 6.52, Coverfilm, 6.53, and Coverlay, 6.54.

6.57 CRITICAL OPERATION – Production process or fabrication step considered potentially detrimental to the materials subject to the operation.

6.58 CURRENT – The flow or movement of electrons in a conductor as a result of a voltage difference between the ends of the conductive path.

6.59 DECLAD – A dielectric material from which the foil or conductive material has been removed by etching or other means.

6.60 DELAMINATION – A planar separation of materials (i.e., separation between conductor and base material, bonding film and base material, cover material and conductor, etc.).

6.61 DESICCATOR – A sealable enclosure containing anhydrous calcium chloride, or other drying agent, maintained at a relative humidity not exceeding 20 percent at 23 ±2 °C (73.4 ±3.6 °F).

6.62 DIELECTRIC – A material capable of high resistance to the flow of electrical current and capable of being polarized by electric field.

6.63 DOUBLE-SIDED – A singlelayer construction or printed wiring board with a conductive layer on the two external sides of the base material. Sometimes referred to as di-clad.

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6.64 EDGE CONDUCTOR – A conductor parallel with and spaced not more than 0.40 mm (0.015 inch) from the edge of the base material.

6.65 ELECTRODEPOSITION – The depositing of conductor material from a plating solution by the application of electrical current.

6.66 ELECTROLESS DEPOSITION – The depositing of conductor material from an autocatalytic plating solution without the application of electrical current.

6.67 ELECTROPLATING – See Electrodeposition, 6.65.

6.68 EMBEDDED COMPONENT – A discrete component integrated into the FMIC during fabrication.

6.69 END-PRODUCT – An individual part or assembly in its final completed state. See End-Use Product, 6.70.

6.70 END-USE PRODUCT – A device or appliance in which an FMIC is installed as a component.

6.71 ETCHANT – A solution used to remove the unwanted portions of material from a base material or FMIC construction by a chemical reaction.

6.72 ETCHED – A base material in which the conductive layer has been removed by a chemical process.

6.73 ETCHING – The chemical, or chemical and electrolytic, removal of unwanted portions of conductive or resistive material.

6.74 EXTERNAL LAYER – The conductor pattern on the external surface of the construction.

6.75 FABRICATOR – A manufacturer, alternate manufacturer, subcontractor, or multi-site processor who may form the pattern of conductive material, laminate, coat, or process the materials for production of a printed wiring board or FMIC.

6.76 FILLET – Material used to fill the corner or angle created, where two materials are joined.

6.77 FILM – A sheet, thin coating, or membrane material having a thickness not greater than 0.25 mm (0.010 inch).

6.78 FLAMMABILITY CLASSIFICATION ONLY – A printed wiring board intended for use where the construction shall be evaluated for flammability classification only, and the thermal, mechanical, and electrical capacity of the materials is not of concern and only the flammability classification of the resulting FMIC is of concern in the end-use product.

6.79 FLAT (PANEL) – Any number of printed wiring board constructions or FMIC's assembled together in a sheet, usually with a frame around the side, when shipped from the FMIC manufacturer.

6.80 FLEXIBLE INTERCONNECT CONSTRUCTION – A sub-category construction intended for use where some portion of the construction shall be subject to flexing in the end-use product application.

6.81 FLEXIBLE MATERIALS INTERCONNECT CONSTRUCTION (FMIC) – An assembly of printed wiring board constructions, and stiffener and adhesive material, where the assembly is intended for component mounting and interconnection purposes.

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6.82 FLEX-TO-INSTALL CONSTRUCTION – A sub-category construction intended for use where some portion of the construction may be subject to flex for installation or service in the end-use product.

6.83 FLUSH-PRESS METAL CONDUCTOR – A metal conductor, such as copper, positioned and secured in a base material by a heat and pressure process.

6.84 FLUX – A surface oxidation removing and protecting compound, used to promote wetting of the base metal surface during soldering operations. Flux shall include, but not be limited to acid flux, inorganic flux, organic flux, and water soluble organic flux.

6.85 FMIC – See Flexible Materials Interconnect Construction (FMIC), 6.81.

6.86 FOIL LAMINATION – A process for bonding a conductive foil to a base dielectric material or other insulating material.

6.87 FREEFILM – An adhesive layer used to bond discrete layers during lamination of multilayer flexible printed wiring board constructions. See Bonding Film, 6.14, and Unsupported Bonding Film, 6.174.

6.88 FULLY-ADDITIVE PROCESS – A fabrication process where the entire thickness of electrically isolated conductors is obtained by electroless deposition.

6.89 GRADE – A designation arbitrarily assigned to a material by the material manufacturer, converter, or vendor.

6.90 GROUND– A common reference point for conductor circuits.

6.91 GROUND PLANE – A conductor plane used as a common reference point for conductor circuits.

6.92 HEATSINK – A device made of high thermal conductivity and low specific heat material capable of dissipating heat generated by a component or assembly.

6.93 HEATSINK PLANE – A continuous sheet of high thermal conductivity and low specific heat material intended to dissipate heat from heat generating components or assemblies.

6.94 HIGH DENSITY INTERCONNECT MATERIALS (HDI) – Thin insulating materials used to support conductor materials requiring mechanical strength from a separate core material and are intended for the production of microvias using sequential build-up and related multilayer interconnect technologies. Some examples of HDI materials: resin coated copper foil (RCF), liquid photoimageable (LPI) dielectric coating materials, photoimageable film dielectric coating materials, and other thin insulating materials when used to support conductor material shall be considered HDI material.

6.95 IDENTICAL PROCESSING – Production or fabrication processes with the same manufacturing steps required to fabricate an FMIC.

6.96 IMMERSION SILVER – Consists of a very thin coating typically less than 0.55 microns (0.0217 mils) of nearly pure silver created by galvanic displacement and may contain a slight amount of organic material deposited with the silver.

6.97 INCLUSIONS – Foreign particles, metallic or nonmetallic, entrapped (cannot be wiped off with a cloth) in the specified material and are not intended as part of the material formulation.

6.98 INFRARED REFLOW (IR) – Melting of tin/lead or remelting of solder using infrared heat as the primary source of energy.

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6.99 INNERLAYER CONNECTION – An electrical connection between two or more internal conductor layers of an FMIC construction.

6.100 INTERLAYER CONNECTION – An electrical connection between two or more conductor layers on or in an FMIC construction.

6.101 INTERNAL LAYER – A conductor pattern contained entirely within a multilayer construction.

6.102 LAMINATE (n.) – The product of bonding two or more layers of material.

6.103 LAMINATE THICKNESS – The thickness of the dielectric material (not including adhesive thickness) in a single-sided or double-sided singlelayer metal-clad base material.

6.104 LAMINATING ADHESIVE – A thin film, coating, or membrane material used to laminate multilayer FMIC's and printed wiring boards.

6.105 LAND – Part of the conductor pattern, usually where components are attached, mounted, or connected.

6.106 LAYER-TO-LAYER SPACING – The thickness of dielectric material between adjacent conductor planes (i.e., the physical distance between adjacent conductor planes).

6.107 LEGEND INK – See Marking Ink, 6.108.

6.108 MARKING INK – A non-conductive permanent coating, resistant to solvents and chemicals, used to provide a means of identification in the form of letters, numbers, symbols and patterns to identify component locations and orientation to aid in printed wiring board assembly.

6.109 MAXIMUM AREA DIAMETER (MAD) – The solid, unpierced circle of conductive material depicted in Figure 12.6 represents the maximum area conductor diameter acceptable for any FMIC conductor pattern. The maximum area conductor diameter is determined by inscribing and measuring the largest circle within the maximum unpierced conductor area of the FMIC conductor pattern.

6.110 MAXIMUM OPERATING TEMPERATURE (MOT) – The maximum continuous use temperature the FMIC may be exposed to under normal operating conditions.

6.111 METAL-CLAD BASE MATERIAL – Base material with integral metal conductor material on one or both sides with or without adhesive.

6.112 MIDBOARD CONDUCTOR – A conductor spaced more than 0.4 mm (0.016 inch) from the edge of a printed wiring board.

6.113 MINIMUM CONDUCTOR WIDTH – The minimum width conductor present on the sample or production printed wiring board. See Conductor Base Width, 6.36.

6.114 MIXED COMPONENT-MOUNTING TECHNOLOGY – A component mounting process incorporating both through-hole and surface mounting on the same FMIC.

6.115 MIXED TECHNOLOGY – A component mounting process incorporating both through-hole and surface mounting on one side of the same FMIC.

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6.116 MULTILAYER – A printed wiring board construction category that consists of alternate layers of conductor and dielectric materials laminated or bonded together, including at least three conductor layers separated by two dielectric layers, with at least one internal conductor layer.

6.117 MULTILAYER RIGID FLEX COMPOSITE – Hybrid FMIC's consisting of a combination of flexible, flex-to-install, and rigid constructions, and in some cases rigid industrial laminate materials, electrically interconnected by means of conductor plated through holes or vias.

6.118 OVERCOAT – A thin coating or membrane material used to cover a conductive pattern on a base material.

6.119 PATTERN – A configuration of conductive and nonconductive materials on a base dielectric material.

6.120 PERFORMANCE LEVEL CATEGORIES (PLC) – An integer defining a range of test values for a given electrical or mechanical property test.

6.121 PERMANENT MATERIALS – Materials intended to be a part of the FMIC for the life of the product.

6.122 PERMANENT RESIST – A solder resist or mask material intended to be a part of the FMIC, for the life of the product.

6.123 PLATED-THROUGH HOLE – A connection between different planes of conductor patterns on double sided, or on or in multilayer FMIC's, by means of a plating process that deposits a conductor material on the side of a hole.

6.124 PLATING (n.) – A chemical or electrochemical deposition of metal on an entire surface or on a conductive pattern.

6.125 PLATING-UP – The electrochemical deposition of a conductive material on a base dielectric material taking place after the base dielectric material has been made conductive.

6.126 PLUGGED-HOLE MATERIAL – A nonmetallic substance used to plug through holes, buried or blind vias, etc., and applied by some process, such as dipping, curtain coating, film laminating, screening, spraying, or melt-flow.

6.127 POLYMER THICK FILM – Referred to in this Standard as conductive paste. See Conductive Paste, 6.31.

6.128 PREPREG – A sheet of material impregnated with a resin cured to an intermediate stage (B-stage resin).

6.129 PRIMARY STAGE OF MANUFACTURE – The point in time when the product is ready for inspection prior to shipment.

6.130 PRINTED BOARD – See Printed Circuit Board, 6.131, and Printed Wiring Board, 6.135.

6.131 PRINTED CIRCUIT BOARD – A printed board produced from rigid industrial laminate material that provides point-to-point connections and printed components in a predetermined arrangement. See the Standard for Printed Wiring Boards, UL 796. See also Printed Wiring Board, 6.135, and Printed Board, 6.130.

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6.132 PRINTED CIRCUIT BOARD ASSEMBLY – An assembly that uses a printed wiring board for component mounting and interconnecting purposes.

6.133 PRINTED CONDUCTOR – A conductor applied to a base material, or to an existing conductor on base material, by means of a printing process.

6.134 PRINTED WIRING – A pattern of conductive material formed on the surface of a base or dielectric material with point-to-point electrical connections or shielding.

6.135 PRINTED WIRING BOARD – A completely processed combination of a printed wiring pattern, including printed components, and the base material. See Printed Circuit Board, 6.131 and Printed Board, 6.130.

6.136 PRINTING – Reproducing a pattern on a surface by any process.

6.137 PRODUCTION BOARD – A complete fabricated FMIC intended for shipment.

6.138 PRODUCTION PROCESS – Fabrication process used to produce FMIC's intended for end-use products.

6.139 REINFORCEMENT MATERIAL – Any material (i.e. fibrous, continuous, sheet, etc.) capable of enhancing the base material mechanical or physical performance.

6.140 RELATIVE THERMAL INDEX (RTI) – Maximum service temperature for a material, where a class of critical property will not be unacceptably compromised through chemical thermal degradation, over the reasonable life of an electrical product, relative to a reference material having a confirmed, acceptable corresponding performance defined RTI.

6.141 RESIN COATED COPPER FOIL (RCF) – Metal foil coated with unreinforced resin using a single- (one pass) or double- (two pass) coated system. Single-coated foils are usually coated with one layer of B-stage resin. Double-coated foils are usually coated with two layers of resin; C-stage resin adjacent to the foil and B-stage resin on the surface of the C-stage resin.

6.142 RESIST COATING – A material supplied in liquid or film form to mask or protect selected areas of a pattern from the effects of an etchant, solder, or plating and which remains on the printed wiring board after processing.

6.143 RIGID – A sub-category construction intended for use where no portion of the construction shall be subject to flexing, bending, or flex-to-install in the end-use product application.

6.144 RIGID INDUSTRIAL LAMINATE – Fibrous reinforcement material impregnated or coated with a thermosetting resin binder, and consolidated under high temperature and pressure into a dense solid product.

6.145 RIGID PRINTED WIRING BOARD – A printed wiring board produced from rigid base dielectric materials.

6.146 ROLL MATERIAL – Flexible materials supplied on a supporting core for the purposes of offwinding for further processing.

6.147 SAMPLE – A test vehicle which may be a production printed wiring board, or a portion there of, or a coupon.

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6.148 SEQUENTIALLY LAMINATED MULTILAYER – A multilayer category construction formed by a build-up of plated through-hole double-sided singlelayer category constructions or multilayer constructions, such that some of the conductive layers are interconnected with blind and/or buried vias.

6.149 SHEET MATERIAL – Flexible materials supplied cut to processing dimensions for further processing. May have been prepunched.

6.149A SHIELDING MATERIAL – A material, usually electrically conductive, that reduces the interaction of electric or magnetic fields upon devices, circuits, or portions of circuits. Shielding properties shall be evaluated during the end product investigation.

6.150 SILVER MIGRATION – The ionic movement of silver due to migration inducing affects.

6.151 SINGLELAYER – Singlelayer constructions are double-sided constructions with one layer of dielectric materials(s) separating the conductor planes, and single-sided constructions with a single conductor plane on one side of a dielectric material(s).

6.152 SINGLE-SIDED – An FMIC construction or printed wiring board with a conductive layer on one external side of the base material(s).

6.153 SOLDER – A metal alloy with a melting temperature below 427 °C (800 °F).

6.154 SOLDER MASK – See Solder Resist, 6.155.

6.155 SOLDER RESIST – A coating material intended to prevent deposition of solder upon selected areas during solder operations.

6.156 SOLDERING – ASSEMBLY SOLDERING PROCESS – The process used for soldering components to a printed wiring board during the assembly process. The soldering process may include but is not limited to reflow, wave, selective soldering or other equivalent soldering techniques.

6.157 SOLDERING – HAND SOLDERING – Hand-held, operator-controlled soldering, usually with a soldering iron.

6.158 SOLDERING – SELECTIVE SOLDERING – An automated process used for soldering components to a printed wiring board during the assembly process. The process targets only selected components on a printed wiring board. The complete printed wiring board may not be subject to the same thermal profile during these soldering processes. Selective Soldering encompasses different techniques but excludes Surface Mount Technology (SMT) reflow soldering and traditional wave soldering. Examples of Selective Soldering are – Laser Soldering, Miniature Wave Select Solder Fountains, and Point-to-Point Robotic Soldering.

6.159 SPUTTERED ON – Metallized pre-polymerized (cured) film. Typically the resin is a thermoset, but may be a thermoplastic.

6.160 STIFFENER – An organic or inorganic material used to provide support or strength to part of an FMIC.

6.161 SUBSTRATE – See Core Material, 6.51.

6.162 SUPPORTED BONDING FILM – A combination of film with integral adhesive on two sides, and a dielectric material used to bond discrete layers during lamination of multilayer category constructions, FMIC's, and printed wiring boards. See Bond ply, 6.16, and Bonding Film, 6.14.

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6.163 SURFACE FINISH – See 6.166, Surface Plating.

6.164 SURFACE MOUNT COMPONENT – A leaded or leadless component capable of being attached to an FMIC construction by surface mounting.

6.165 SURFACE MOUNTING – Electrical connection of components on the surface of the conductor pattern.

6.166 SURFACE PLATING – The surface plating/coating shall be on the top surface of patterned conductors and shall not create an interface with the dielectric surface.

6.167 TEMPERATURE PROFILE – The depiction of temperatures a select point traverses as it passes through a process involving multiple temperatures and dwell times.

6.168 TEST PATTERN – The conductor pattern intended for test and inspection purposes.

6.169 TEST SAMPLE – A complete (or portion of a) production FMIC, a complete (or portion of a) panel of FMIC's, or a coupon or panel of coupons (or a portion thereof) formed by the FMIC production processes incorporating specific features.

6.170 TYPE – A unique model or product designation arbitrarily assigned to an FMIC by the fabricator. See Markings, Section 13.

6.171 UNDERCOAT – A thin coating or membrane material between conductor planes intended for use as a dielectric material, used to cover a conductive pattern on a base material, or some portion thereof, and conductor material is applied to the exposed undercoat surface.

6.172 UL/ANSI TYPE MATERIAL – A specific type designation for materials defined in the Standard for Polymeric Materials – Industrial Laminates, Filament Wound Tubing, Vulcanized Fibre, and Materials Used in Printed Wiring Boards, UL 746E, and the Standard for Polymeric Materials – Flexible Dielectric Film Materials For Use In Printed Wiring Boards and Flexible Materials Interconnect Constructions, UL 746F, as having certain base material, resin, thermal index and profiles of minimum performance.

6.173 UNCLAD – A dielectric material without foil or conductive material (never copper clad).

6.174 UNSUPPORTED BONDING FILM – A coating or membrane adhesive material used to bond discrete layers during lamination of multilayer category constructions, FMIC's, and printed wiring boards. See Bonding Film, 6.14, and Freefilm, 6.87.

6.175 VIA – A conductor plated through-hole, in which there is no intent to insert a component lead or other reinforcement material, for interlayer connection of conductor planes. See also Blind Via, 6.12, and Buried Via, 6.19.

6.176 VOID – The absence of metallic or nonmetallic substance in a localized area, in or on an FMIC.

6.177 X-AXIS – A reference axis, usually horizontal or left-to-right direction in a two dimension coordinate system. The x and y axes are usually perpendicular to one another in a two or three dimension coordinate system.

6.178 Y-AXIS – A reference axis, usually vertical or bottom-to-top direction in a two dimension coordinate system. The x and y axes are usually perpendicular to one another in a two or three dimension coordinate system.

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6.179 Z-AXIS – The axis perpendicular to the plane created by the x and y reference axes. This axis usually refers to the thickness of an FMIC.

7 Abbreviations

7.1 The acronym FMIC appears throughout the Standard, and stands for "Flexible Materials Interconnect Construction." See 6.80 for the definition of FMIC.

7.2 The acronym MAD appears throughout the Standard, and stands for "Maximum Area Diameter." See 6.109 for the definition of MAD.

7.3 The acronym MOT appears throughout the Standard, and stands for "Maximum Operating Temperature." See 6.110 for the definition of MOT.

7.4 The acronym RTI appears throughout the Standard, and stands for "Relative Thermal Index." See 6.140 for the definition of RTI.

CONSTRUCTION

8 Materials

8.1 General

8.1.1 Flexible materials shall be defined as materials exhibiting flexible properties.

8.1.2 Each combination of materials, and each applicable material component, film, adhesive, base material, conductor material, bonding film, cover material, dielectric material, laminate, prepreg, stiffener, and other insulation material in a fabricated FMIC shall be determined to be acceptable for use in the intended construction (sub-category) application.

Exception: For the intended application, if the applicable material combinations, in the minimum and maximum build-up construction have previously been evaluated with representative parameter profile indices to the applicable testing requirements in accordance with the Standard for Polymeric Materials – Flexible Dielectric Film Materials, UL 746F, then the (Ambient) bend test, 12.9; Cold-bend test, 12.10; and Repeated flexing test, 12.11; need not be conducted. The Bond strength test, 12.6; Coverlay test, 12.8; and Flammability tests, 12.15; of the minimum build-up construction shall be conducted for the FMIC type.

8.1.3 FMIC test samples shall be provided for each different manufacturer and each different grade of material, for each material component, except as described in 8.1.9.

8.1.4 Each material component shall be identified by the manufacturer, grade designation, and generic material type (i.e. polyimide, polyester, epoxy, acrylic, copper, etc.).

8.1.5 The material components, in an as-received condition, shall be free of defects such as unevenness in the base dielectric material, non-uniformity in any fabric weave or exposure of fibers or threads if applicable, and shall be evenly coated, without pinholes, blisters, voids.

8.1.6 If a difference in a grade designation or catalog number of the same material reflects a minor change such as a change of color or a different manufacturing location for the same supplier, and the difference or minor change does not affect the material performance profile indices, samples need not be provided for both materials and a separate unique Type designation is not required for the FMIC type.

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8.1.7 Film, adhesive, base material, bonding film, cover material, dielectric material, coating, laminate, prepreg, stiffener, and other insulation material used as a base material and/or dielectric barrier, in an FMIC shall have acceptable electrical and mechanical relative temperature indices and direct support performance properties at or above the MOT of the FMIC type. The electrical and mechanical relative temperature indices shall be determined in accordance with the Standard for Polymeric Materials – Industrial Laminates, Filament Wound Tubing, Vulcanized Fibre, and Materials Used in Printed Wiring Boards, UL 746E or the Standard for Polymeric Materials – Flexible Dielectric Film Materials for Use in Printed Wiring Boards and Flexible Materials Interconnect Constructions, UL 746F.

Exception No. 1: If the FMIC type is evaluated for flammability classification only without consideration of an MOT, the materials and applicable material components need not possess electrical and mechanical relative temperature indices or direct support performance properties.

Exception No. 2: If the mechanical and electrical relative temperature indices of the base dielectric material are equal to or exceed the MOT of the FMIC type, the adhesive on one or both sides of the base dielectric material need not possess mechanical and electrical relative temperature indices.

8.1.8 The MOT shall not exceed the electrical or mechanical relative temperature indices of the base material or other insulation material when used as a dielectric barrier and/or substrate for conductors. Suggested values for the MOT include 90, 105, 130, and 150 °C (194, 221, 266, and 302 °F).

8.1.9 Each combination of materials, including each applicable material component in the fabricated FMIC shall be determined to have the same or higher flammability classification as the FMIC type.

8.1.10 The performance profile indexing values of the FMIC type shall be limited to the lowest rated individual indexing values for the dielectric materials in the construction for each combination of materials, including each applicable material component.

8.1.11 If the base material, bonding film, and cover material are manufactured with the same base dielectric material and adhesive (if applicable), and the same conductor material is bonded to the base dielectric material or adhesive, bond strength testing of the conductor to base material shall represent bond strength testing of the conductor to the bonding film and cover material.

8.1.12 When conductor material is laminated or adhered directly to materials such as bonding film, cover material and other insulating material, the resultant combination of insulating material and conductor materials shall be considered base material. See Base Materials, 8.3.

8.1.13 Each material component in combination with each applicable combination of base material, film, adhesive, bonding film, cover material and other insulation material intended in the construction shall comply with the flammability tests in accordance with the Standard for Tests for Flammability of Plastic Materials for Parts in Devices and Appliances, UL 94, according to the desired flammability classification.

Exception No. 1: If the absolute minimum film with the absolute maximum adhesive thicknesses are not intended for production, two sets of samples shall be subject to flammability testing. The first set of samples shall include the absolute minimum film with the corresponding maximum adhesive thickness (which may not be the absolute maximum adhesive thickness to be used in production.) The second set of samples shall include the absolute maximum adhesive thickness with the corresponding minimum film thickness (which may not be the absolute minimum film thickness to be used in production.)

Exception No. 2: If the polyimide film material used to manufacture the base material, bonding film, and/or cover material has been previously evaluated for flammability in the minimum and maximum thickness and the flammability classification is V-0 or VTM-0, flammability testing of the minimum film with the maximum adhesive shall be required assuming the requested flammability rating is the same as the original rating.

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Exception No. 3: If the film material used to manufacture the base material, bonding film, and/or cover material has been previously evaluated for flammability in the minimum and maximum thickness and the flammability classification is VTM-1, VTM-2, V-1, V-2, or HB, double-sided and single-sided flammability samples are required.

8.2 Polyimide ANSI-like flammability program

8.2.1 The program applies to flammability testing only.

8.2.2 When the alternate adhesiveless dielectric material (film) or alternate dielectric material and adhesive combination (film and adhesive) have been previously investigated for flammability classification in accordance with the Standard for Tests for Flammability of Plastic Materials for Parts in Devices and Appliances, UL 94, and/or the Standard for Polymeric Materials – Flexible Dielectric Film Materials for Use in Printed Wiring Boards and Flexible Materials Interconnect Constructions, UL 746F, flammability testing is not required to add alternate film to an established FMIC when the alternate film or alternate film and adhesive combination meets the following requirements:

a0) The FMIC fabricator shall have been previously investigated for a FMIC construction using a polyimide film, with the fabricator's own process and parameters, including minimum and maximum film thickness, minimum and maximum adhesive thickness (if applicable), and flammability classification.

a) The alternate film shall be polyimide;

b) The alternate film shall be adhesiveless or used with the same adhesive and same maximum adhesive thickness as the FMIC fabricator's previously evaluated film;

b1) The desired minimum thickness of the alternate film shall be equal to or greater than the FMIC fabricator's existing minimum film thickness.

c) The alternate film minimum thickness shall be equal to or less than the FMIC fabricator's existing minimum film thickness;

d) The alternate film maximum thickness shall be equal to or greater than the FMIC fabricator's existing maximum film thickness;

e) The alternate film shall have a V-0 or VTM-0 flammability rating the same as the FMIC fabricator's existing film; and

f) The alternate film, or alternate film and adhesive combination, shall have a flammability rating equal to the FMIC fabricator's existing flammability rating.

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8.3 Base materials

8.3.1 Reference to base materials in this Standard shall apply to materials used to support conductor materials, with or without the use of adhesive materials.

8.3.2 Base materials shall include but not be limited to base dielectric materials, such as film, adhesive (where applicable), and substrate materials supporting conductor material. See Figure 8.1 for examples of base materials used in FMIC constructions.

Figure 8.1

Examples of Base Materials, Used in FMIC Constructions

Single-sided base material;
base dielectric material;
conductor-clad with adhesive

Single-sided base material;
base dielectric material;
conductor-clad without adhesive

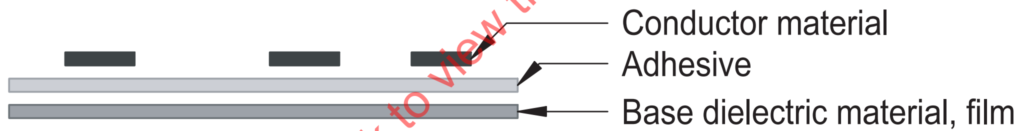
Double-sided base material;
base dielectric material;
conductor-clad with adhesive

Double-sided base material;
base dielectric material;
conductor-clad without adhesive

Bond ply used as base material

Coverfilm used as base material

Where,



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